FMECA End-effects

TSU CONS Reliability Study Progress Meetings #7



List of contents

- 1. End-effects in this FMECA.
- 2. Failure rates & details of <u>TSU</u> end-effects categories.
- 3. Failure rates of <u>TSU RTM</u> end-effects categories.
- 4. TSU Hybrid MC model.
- 5. Questions and next steps.



End-effects in TSU FMECA Categories of failure modes' effects in the table

All options assigned to failure modes:

- Unpredictable
- Asynchronous Beam Dump
- Synchronous Beam Dump
- Downtime
- Loss of injection permit
- No diagnositcs (RTM only)
- No effects

Requirements:

- → 1 failure in **1,000 years** (≅ 114 FITS)
- \longrightarrow 1 failure in **10 years** (\cong 11,400 FITS)

→ 1 failure in **1 year** (≅ 114,000 FITS)

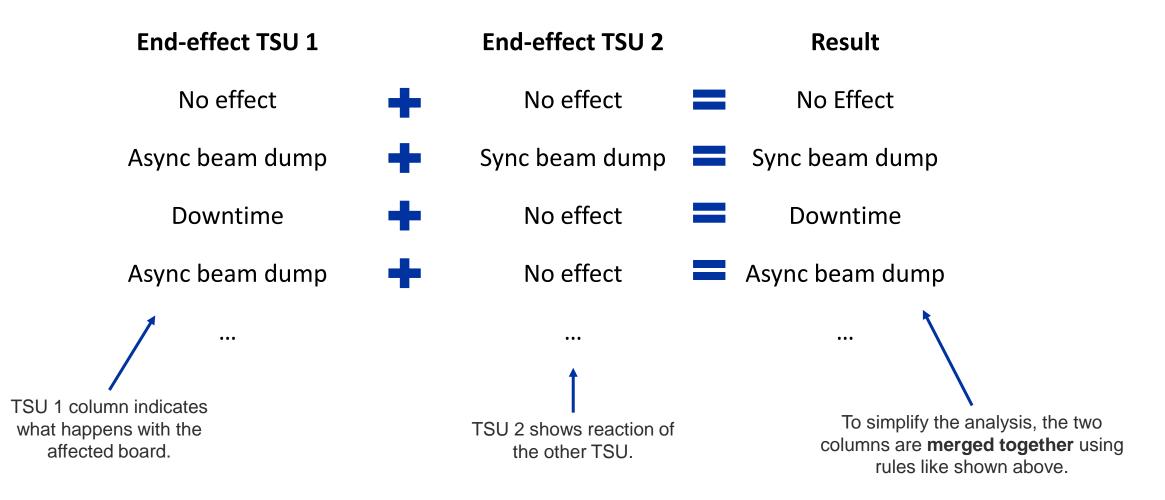
- → no requirement
 - no requirement

FIT – number of failures in 10^9 hours (\cong 115,000 years)



Less critical

Combining end-effects between TSUs TSU1 and TSU2

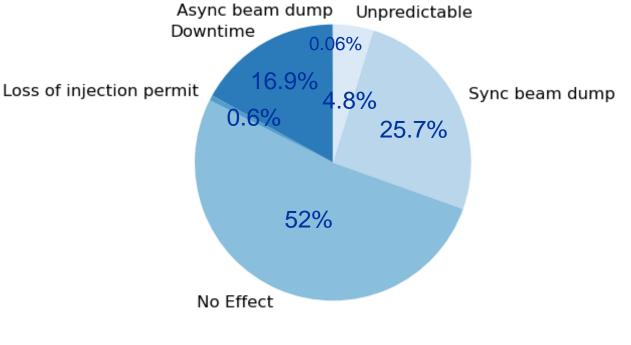




End-effects identified in TSU FMECA Breakdown of total FITS

Unpredictable - 109 FIT **Asynchronous Beam Dump** – 1 FIT Synchronous Beam Dump - 594 FIT **Downtime** - 390 FIT Loss of injection permit – 14 FIT **Total (with effects)** - 1,106 FIT No effect - 1,202 FIT*

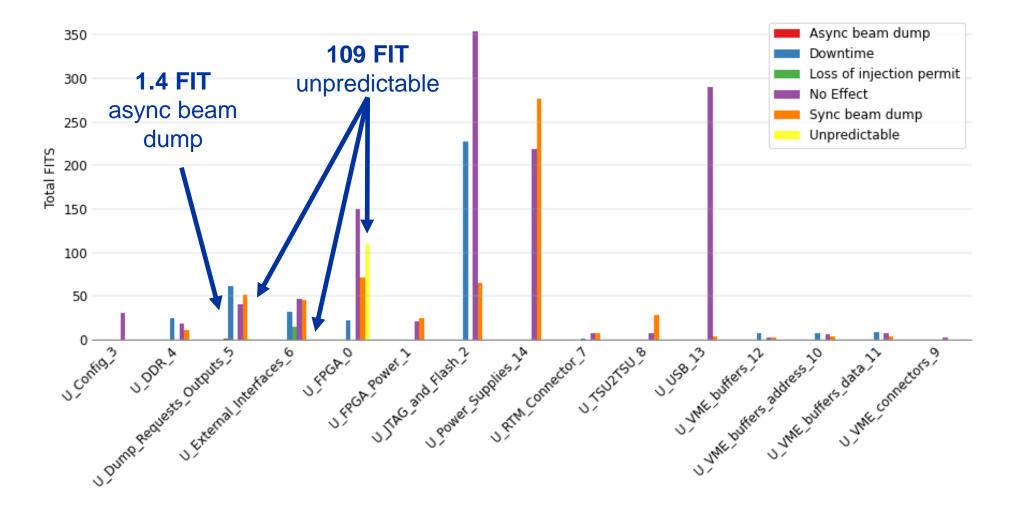
* Without 8 rotary switches (each 8041 FIT according to 217Plus, total – 64,328 FIT)



FIT – number of failures in 10^9 hours (\cong 115,000 years)



FITS in TSU design pages FIT – number of failures in 10⁹ hours





TSU End-effect: Unpredictable

Failure rate: 109 FITS.

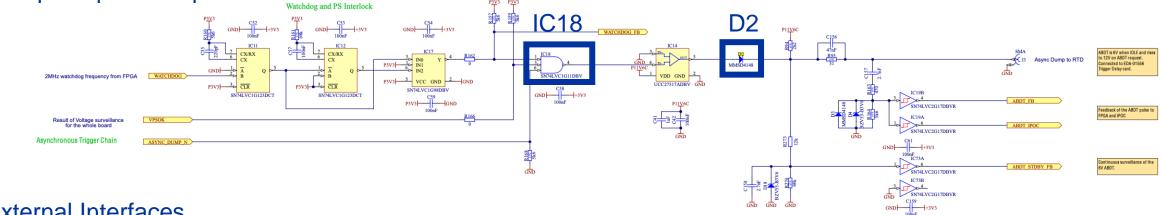
Causes:

- **Parameter change** of a switching diode, D2, in *Dump Requests Output:* 2.9 FITS.
- Parameter change of an AND gate, IC18, in *Dump Requests Output:* 1.4 FITS.
- Open, param. change, stuck high/low of Artix 7 FPGA, IC1: 27 FITS x 4.
 - Exact effect depending on the pin.
- Parameter change of the RS-485 Transceiver, IC41, in *External Interfaces:* 1.4 FITS.

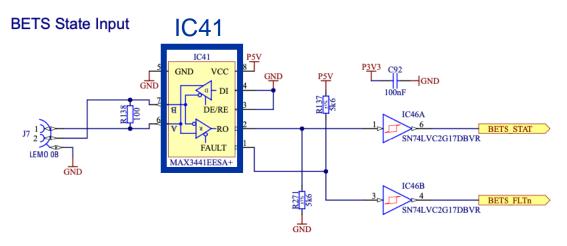


TSU End-effect: Unpredictable Locations

Dump Request Outputs



External Interfaces





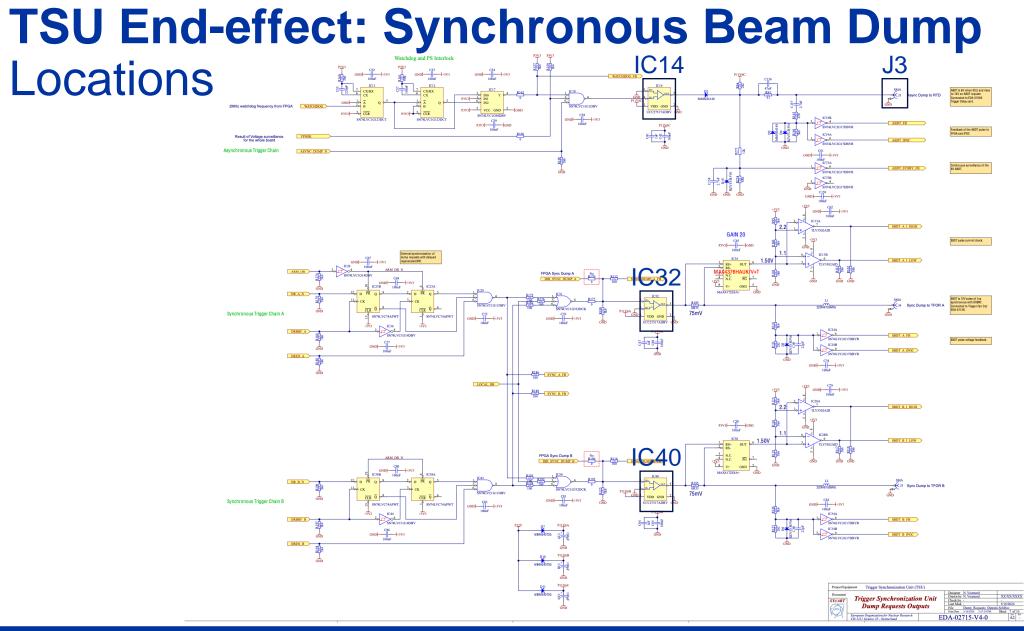
TSU End-effect: Asynchronous Beam Dump

Failure rate: 1.4 FIT.

Causes:

- Stuck high or parameter change in gate drivers, IC14, IC32, IC40, in *Dump Requests Outputs*: 0.2 or 0.5 FIT.
- Open, poor contact/intermittent, short in PCB Jack, J3, in *Dump Requests Outputs*: 0.2 FIT.







TSU End-effect: Synchronous Beam Dump

Total: 594 FITS.

Top contributors:

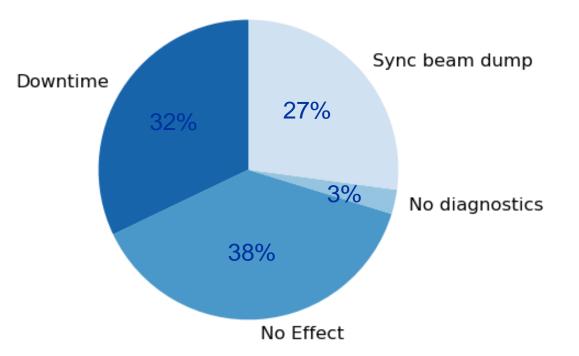
- Short in temperature monitors, IC6: 56 FITS.
- **Short** in Artix-7 FPGA, IC1: 27 FITS.
- Failures in transistors T11, T12: 22 FITS.
- Failures of fuses F1, F2, F3: 20 FITS.

Remaining components' failure rates are below 20 FITS.



End-effects identified in TSU RTM FMECA Breakdown of total FITS

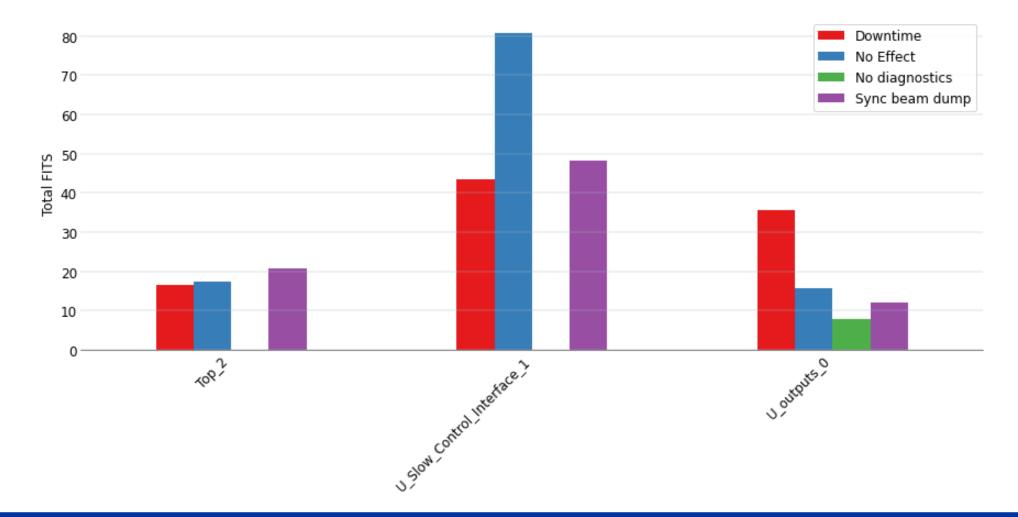
Synchronous Beam Dump	– 83 FIT
Downtime	– 99 FIT
No diagnostics	– 8 FIT
Total (with effects)	– 190 FIT
No effect	– 118 FIT



FIT – number of failures in 10^9 hours (\cong 115,000 years)



FITS in TSU RTM design pages FIT – number of failures in 10⁹ hours



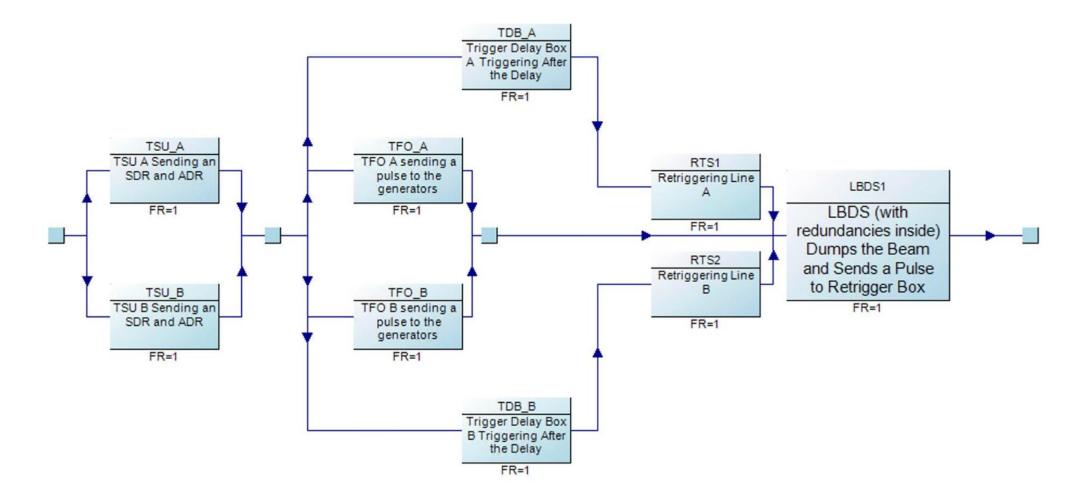


TSU Hybrid MC Model

FMECA inputs for the model



TSU Hybrid MC Model Asynchronous beam dump not triggered by BIS





Failure rates to be used in the model Can "no effect" lead to an effect?

Certain failure modes are assigned "no effect" and "no effect" but lead to loss of redundancy.

Example:

- **A.** Fuses F4 and [F5], param. change or short: assigned "no effect", "no effect", with comment: "loss of SBDT1[2] path".
- **B.** Switching diode D2, open: "no effect", with comment: "Loss of ABDT path".

Can failure modes like this "linger" in the system unnoticed?

 On the other hand, there is "loss of SBDT1 path" with async dump of a gate driver stuck high – but that one triggers an synchronous beam dump, therefore – it is safe as



Questions and next steps

- 1. Can all of the faults in the "unpredictable" end-effects category lead to missed dumps?
- 2. Rotary switches (high failure rate estimation and past experience):
 - 1. Are their faults at the start of operation also not impacting the functionalities of TSU?
 - 2. Will their faults require follow-ups and card replacements?

- Understanding of repair and inspection strategies.
- Hybrid MC model for missing a beam dump (1 in 1,000 years) when not triggered by the BIS.





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